

CAPABILITIES OVERVIEW

	Standard Capabilities	Advanced Capabilities
Layer Count	0-16 Layers	16 +
Board Material	FR4 Standard (Isola, ITEQ, Nelco) FR4 High Temp Rogers 3000 Series Rogers 4000 Series Rogers RT Duroid Series Polyimide (Arlon-Med, Nelco) Halogen Free (Nelco) Arlon-Med PTFE Laminates	Rogers TMM Laminate Series Taconic (TLY - 5, etc.)
Board Thickness	2-Layer Min .015" Max .200" 4-Layer Min .020" Max .200" 6-Layer Min .031" Max .200" 8-Layer Min .047" Max .200" 10-Layer Min .062" Max .200" 12-Layer Min .062" Max .200" 14-Layer Min .062" Max .200" 16-Layer Min .062" Max .200"	2-Layer Min .008" Max .250" 4-Layer Min .015" Max .250" 6-Layer Min .025" Max .250" 8-Layer Min .031" Max .250" 10-Layer Min .040" Max .250" 12-Layer Min .047" Max .250" 14-Layer Min .054" Max .250" 16-Layer Min .062" Max .250" 18 Layers and up - Please Call
Max Board Size		
2-6 Layer	20 x 23	22.2 x 26.2
8-10 Layer	20 x 23	22.2 x 26.2
12-16 Layer	20 x 23	22.2 x 26.2
18 Layer Plus	-	Call
Board Finish Plating	HASL - Leaded HASL - Lead Free Bare Copper Nickel Electrical Nickel Immersion Gold Electrolytic Soft or Hard Gold Immersion Silver Carbon Ink	Wire Bondable Soft Gold OSP White Tin Selective Gold
Finished CU Weight / Trace/Space		
Outer layers	1 oz. Cu - (Min .005" Trace/Space) 2 oz. Cu - (Min .008" Trace/Space) 3 oz. Cu - (Min .012" Trace/Space) 4 oz. Cu - (Min .014" Trace/Space)	.5 oz. Cu - (Min .003" Trace/Space) 1 oz. Cu - (Min .004" Trace/Space) 2 oz. Cu - (Min .006" Trace/Space) 3 oz. Cu - (Min .010" Trace/Space) 4 oz. Cu - (Min .012" Trace/Space) 5 oz. Cu - (Min .014" Trace/Space)
Inner layers	.5 oz Cu - (Min .004" Trace/Space) 1 oz. Cu - (Min .005" Trace/Space) 2 oz. Cu - (Min .006" Trace/Space)	3 oz. Cu - (Min .010" Trace/Space) 4 oz. Cu - (Min .012" Trace/Space)
Inner Layer Clearances	.008"	.005"

CAPABILITIES OVERVIEW (cont.)

Smallest Finished Hole Size		
	Final Thickness <=.062" .008" Hole	Final Thickness <=.062" .006" Hole
	Final Thickness 093" .012" Hole	Final Thickness <=.125" .008" Hole
	Final Thickness .125" .015" Hole	Final Thickness <=.200" .014" Hole
Aspect Ratio for Drill		
	10:1	15:1
Gold Fingers		
	1 Edge	
	2 Edges	
Soldermask Types		
	LPI	Peelable
LPI Soldermask Colors		
	Green	Top & Bottom Mix
	Blue	Side to Side Mix
	Green Matte	
	Black	
	Red	
	White	
Silkscreen Colors		
	White	Top & Bottom Mix
	Yellow	Red
	Black	
CNC Functions		
	Skip Scoring > .25" Spacing	Scoring Panel Edge to Panel Edge
	30 Degree, Std Score Angle	30 & 45 Degree Countersinks
	60, 82, 90, 100 Degree Countersink	Milling/Offset or Recessed Beveling
	15, 20, 30, 45 Degree Gold Finger Bevel	Micro Vias/Laser Drilling (Min. Aspect Ratio 8:1)
	Countersinks (Plated/Non Plated)	Tab Route
	Countersbores (Plated/Non Plated)	Arrayed Panelization
	Castellated Barrels Min .040"	Scored Panelization
Other Services		
	Blind/Buried Vias	Single Sided Score
	Plugged Vias	Selected Plated Edges
	Controlled Dielectric	Plated Slots Min .012" Drilled or Routed
	Plated Edges	Conductive/Non-Conductive Filled Vias
	Tented Vias	.003" Cores
	Gold Fingers up to 18" Long	Mixed Copper Weights
	Microsectioning	
Controlled Impedance		
	0-16 Layers	16 + Layers
	Single-ended % +/- 10	Single-ended % +/- 5
	Differential, Edge Coupled % +/- 10	Differential, Edge Coupled % +/- 5
	Differential, Broadside-Couple % +/- 10	Differential, Broadside-Couple % +/- 10
Quality and Testing		
	IPC Class 2	
	IPC Class 3	
	ISO 9001:2008	
	Netlist Generation	
	TDR Testing	
	UL	